



US00D353817S

# United States Patent [19]

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Wada

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[54] **HEADPHONE**

[75] Inventor: **Joh Wada, Tokyo, Japan**

[73] Assignee: **Sony Corporation, Tokyo, Japan**

[\*\*] Term: **14 Years**

[21] Appl. No.: **4,444**

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[30] **Foreign Application Priority Data**

Aug. 28, 1992 [JP] Japan ..... 4-25511  
 [52] U.S. Cl. .... **D14/205**  
 [58] Field of Search ..... D14/205; 381/183, 187,  
 381/188; 379/430, 444

[56] **References Cited**

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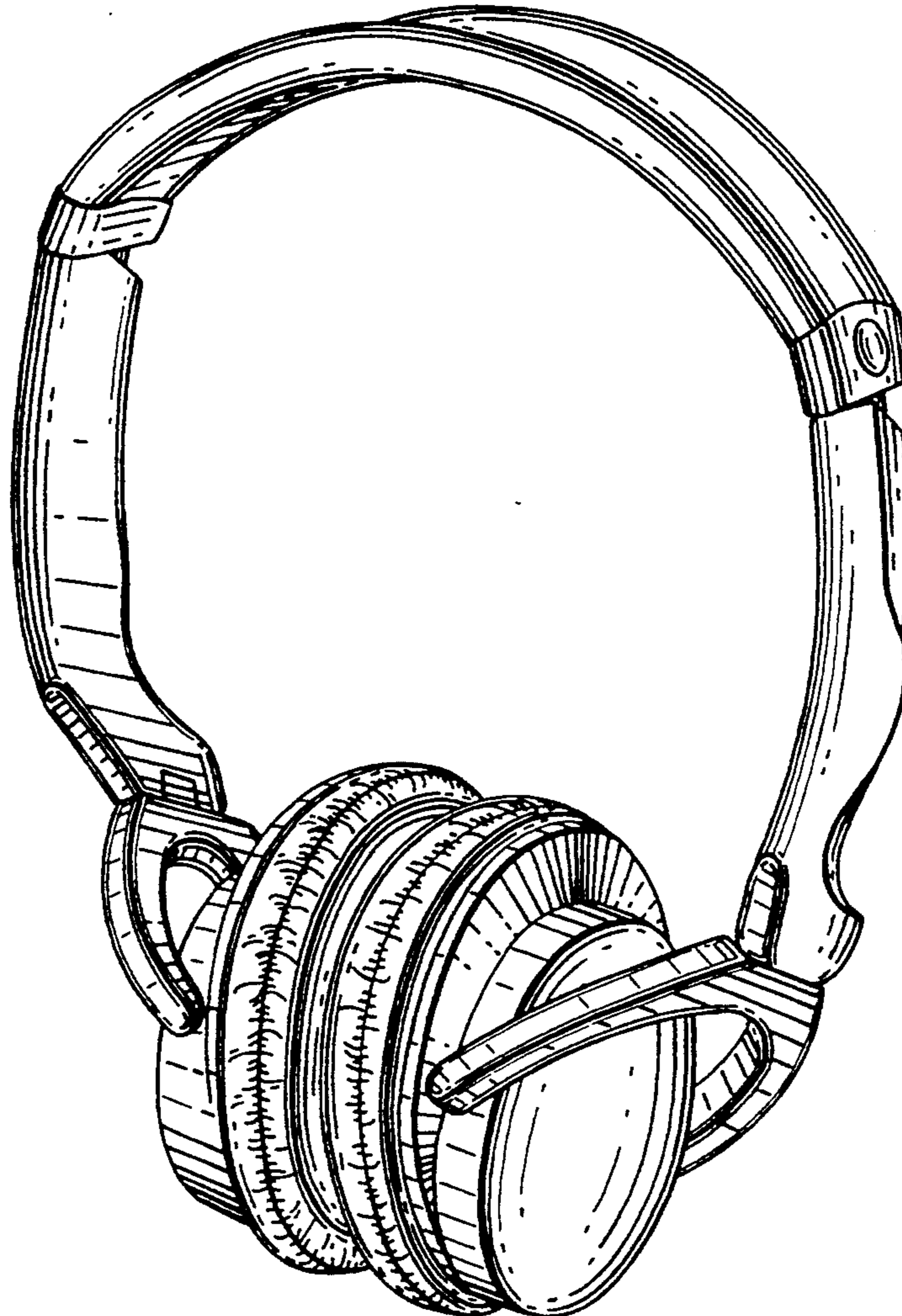
*Primary Examiner*—B. J. Bullock  
*Attorney, Agent, or Firm*—Jay H. Maioli

[57] **CLAIM**

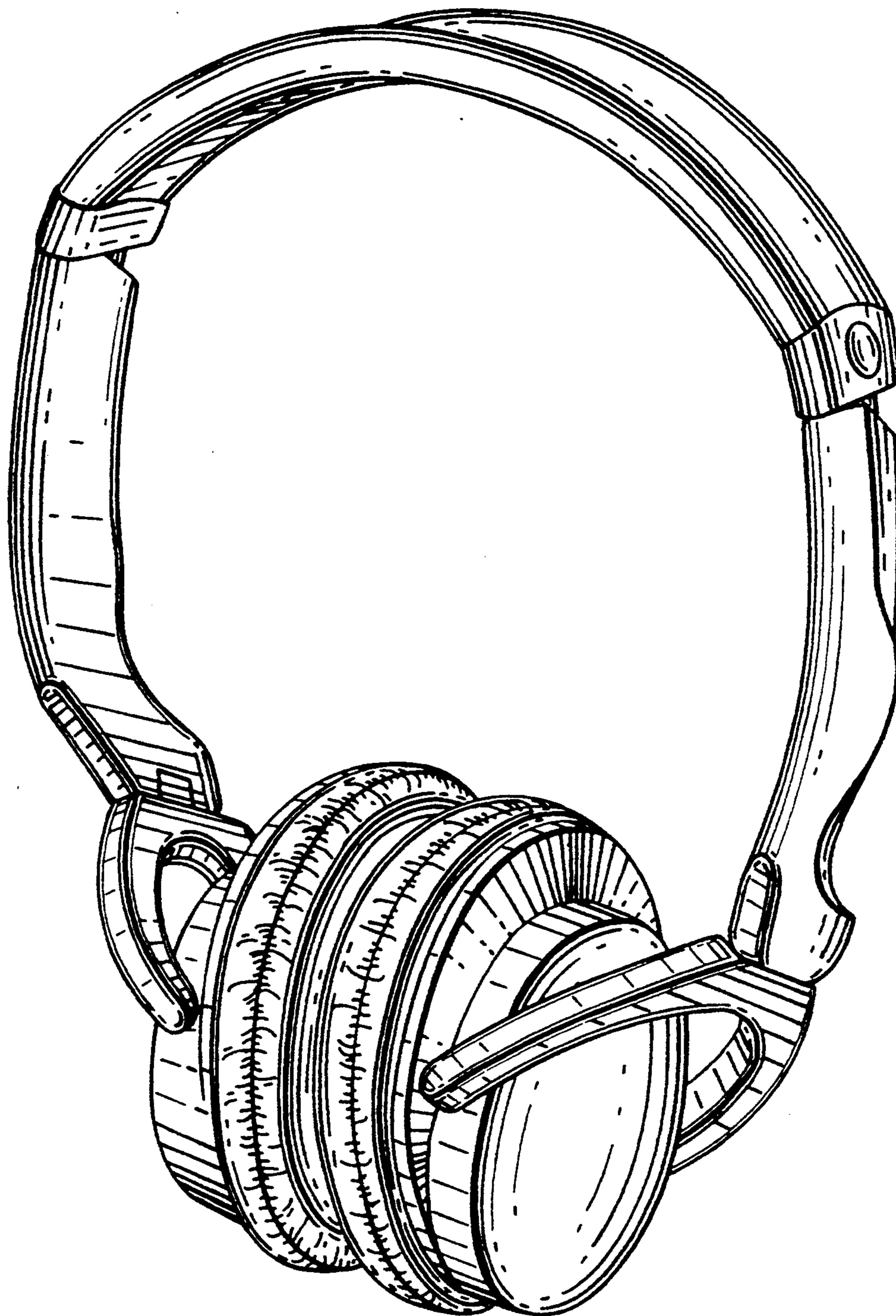
The ornamental design for a headphone, as shown and described.

**DESCRIPTION**

FIG. 1 is a top, front and right-side perspective view of a headphone, showing my new design;  
 FIG. 2 is a top, front and right-side perspective view thereof, shown in the folded position;  
 FIG. 3 is a reduced front elevational view thereof;  
 FIG. 4 is a reduced rear elevational view thereof;  
 FIG. 5 is a reduced left side elevational view thereof;  
 FIG. 6 is a reduced right side elevational view thereof;  
 FIG. 7 is a reduced top plan view thereof; and,  
 FIG. 8 is a reduced bottom plan view thereof.



*FIG. 1*



*FIG. 2*

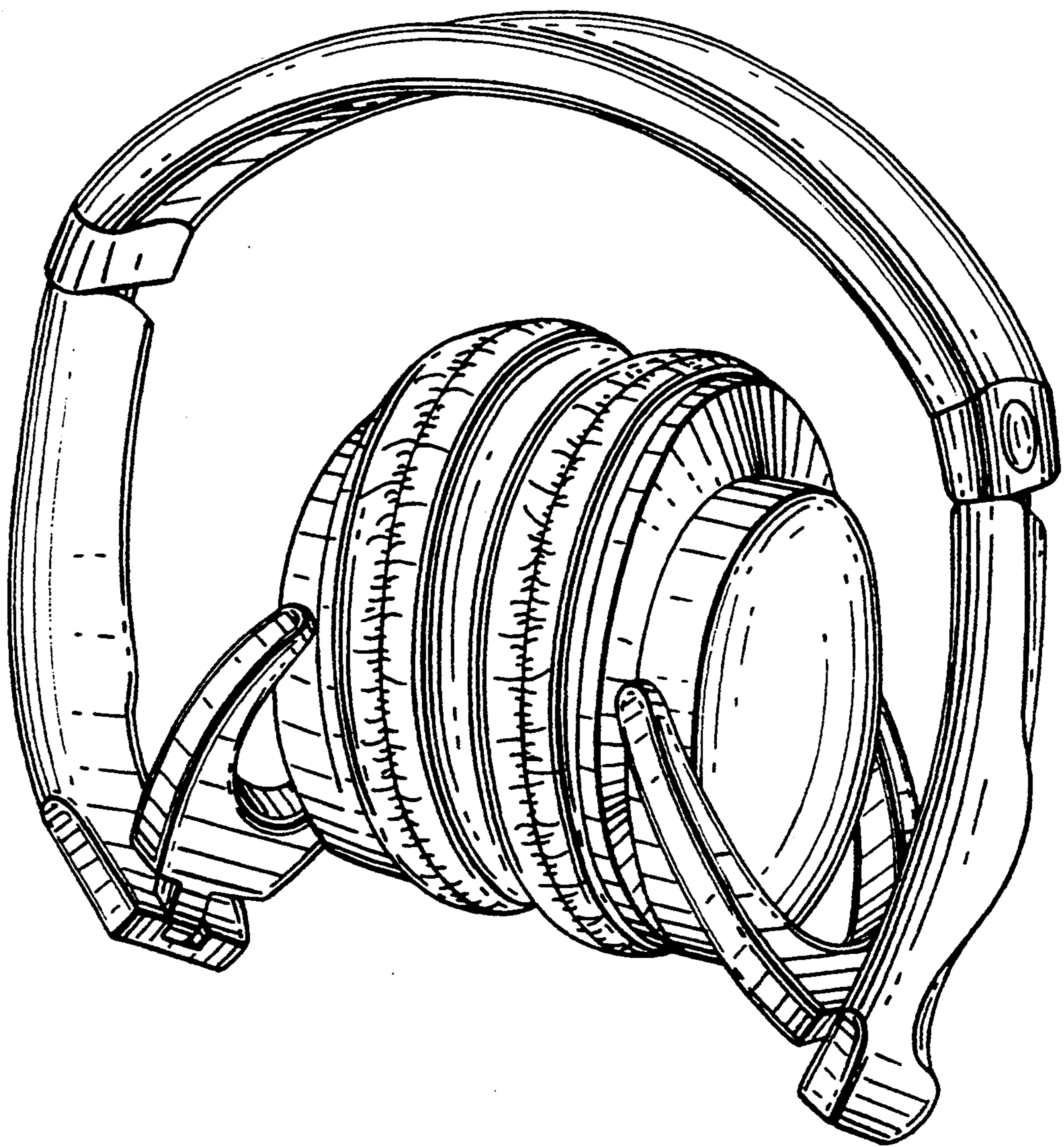


FIG. 3

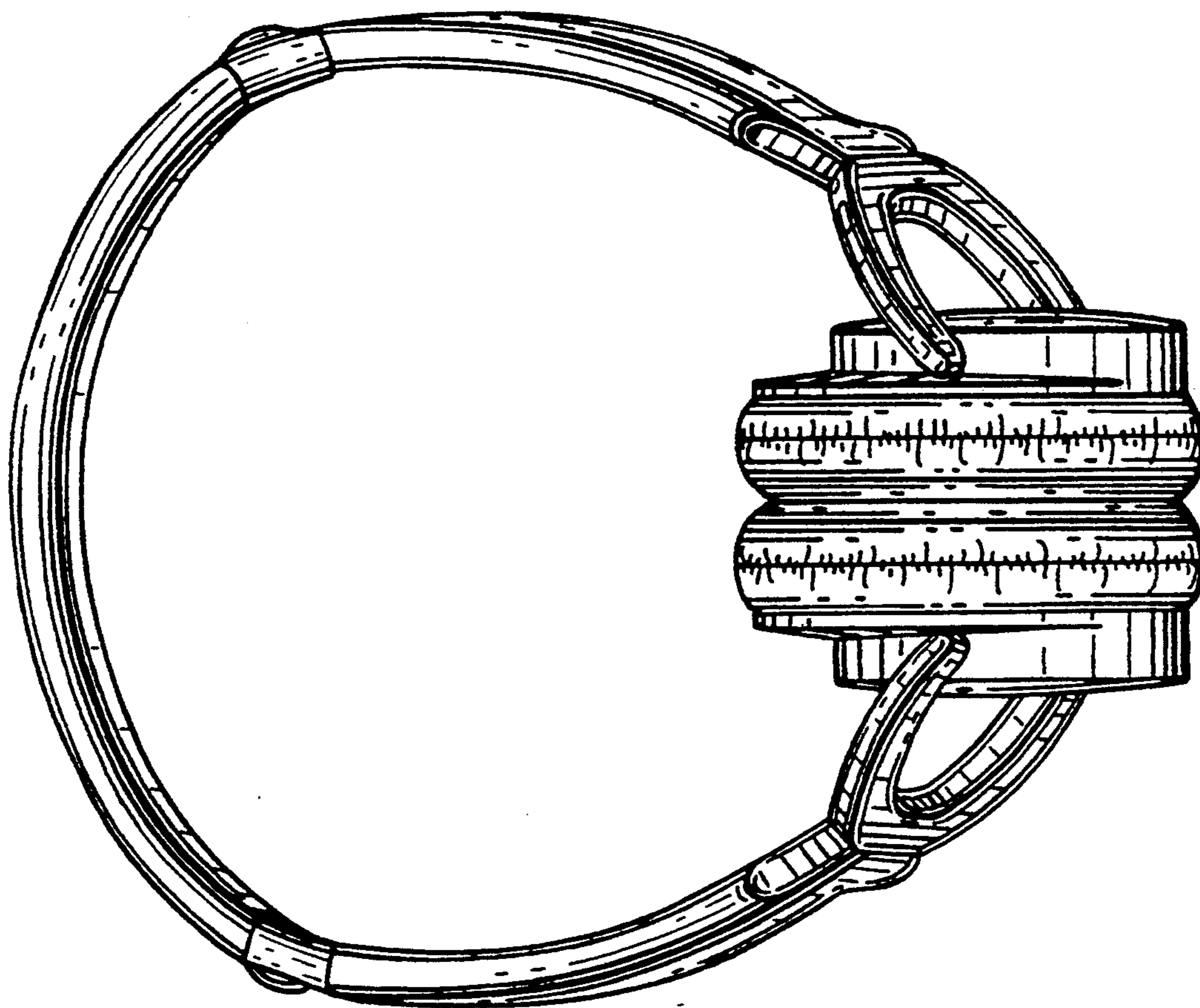
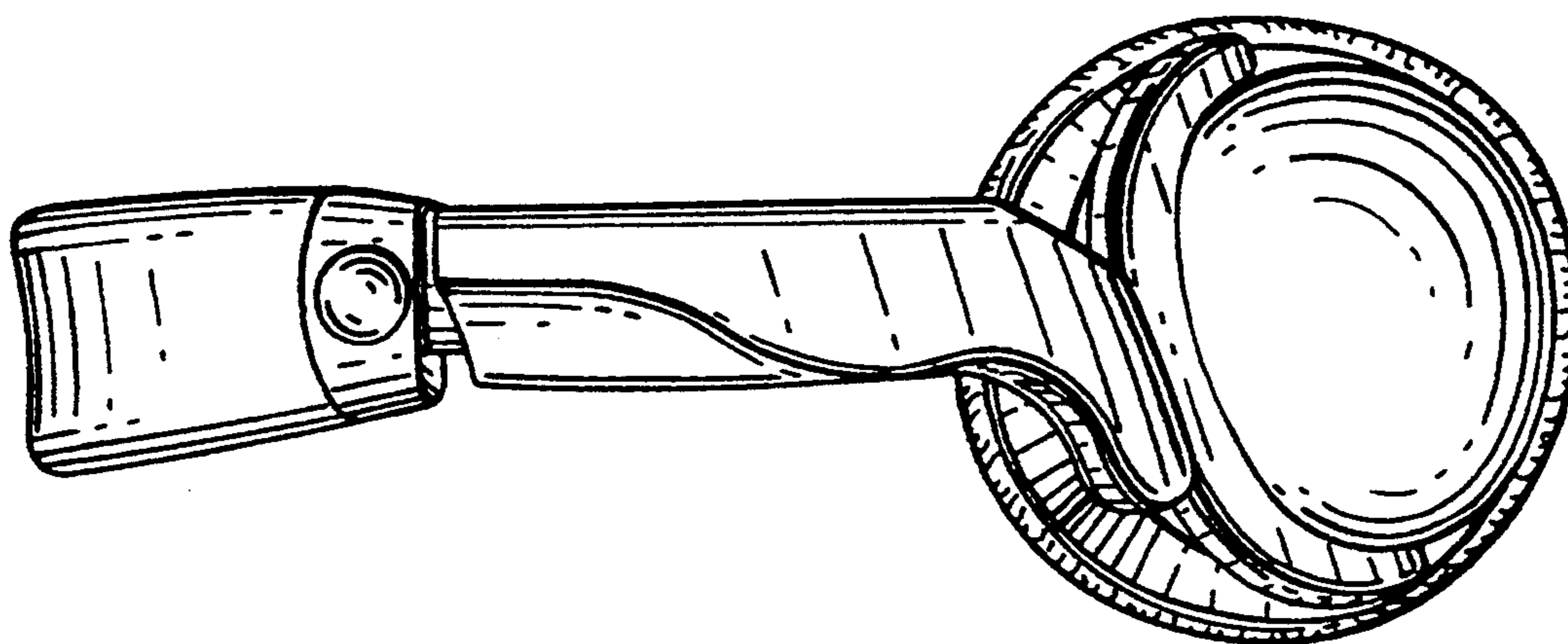
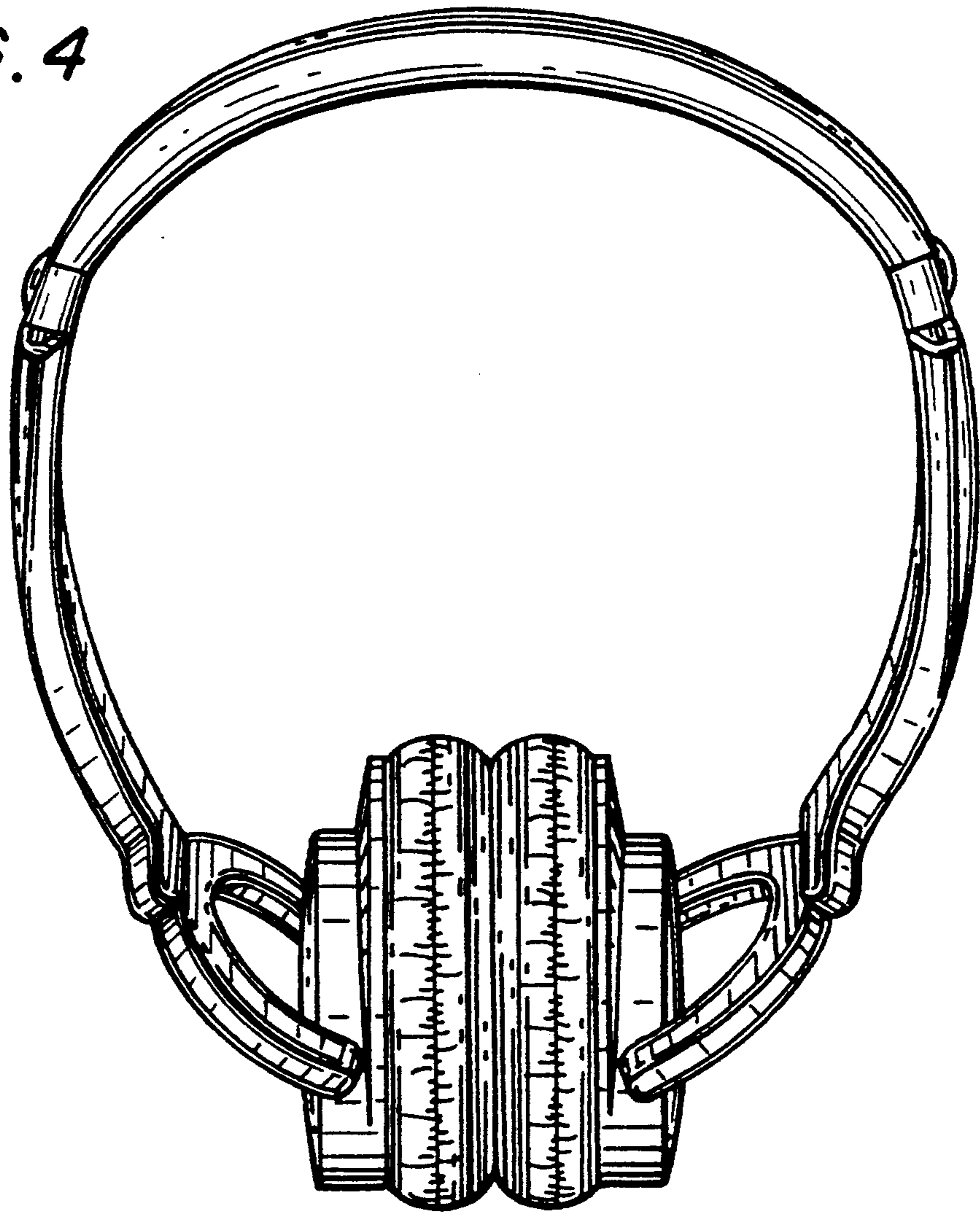


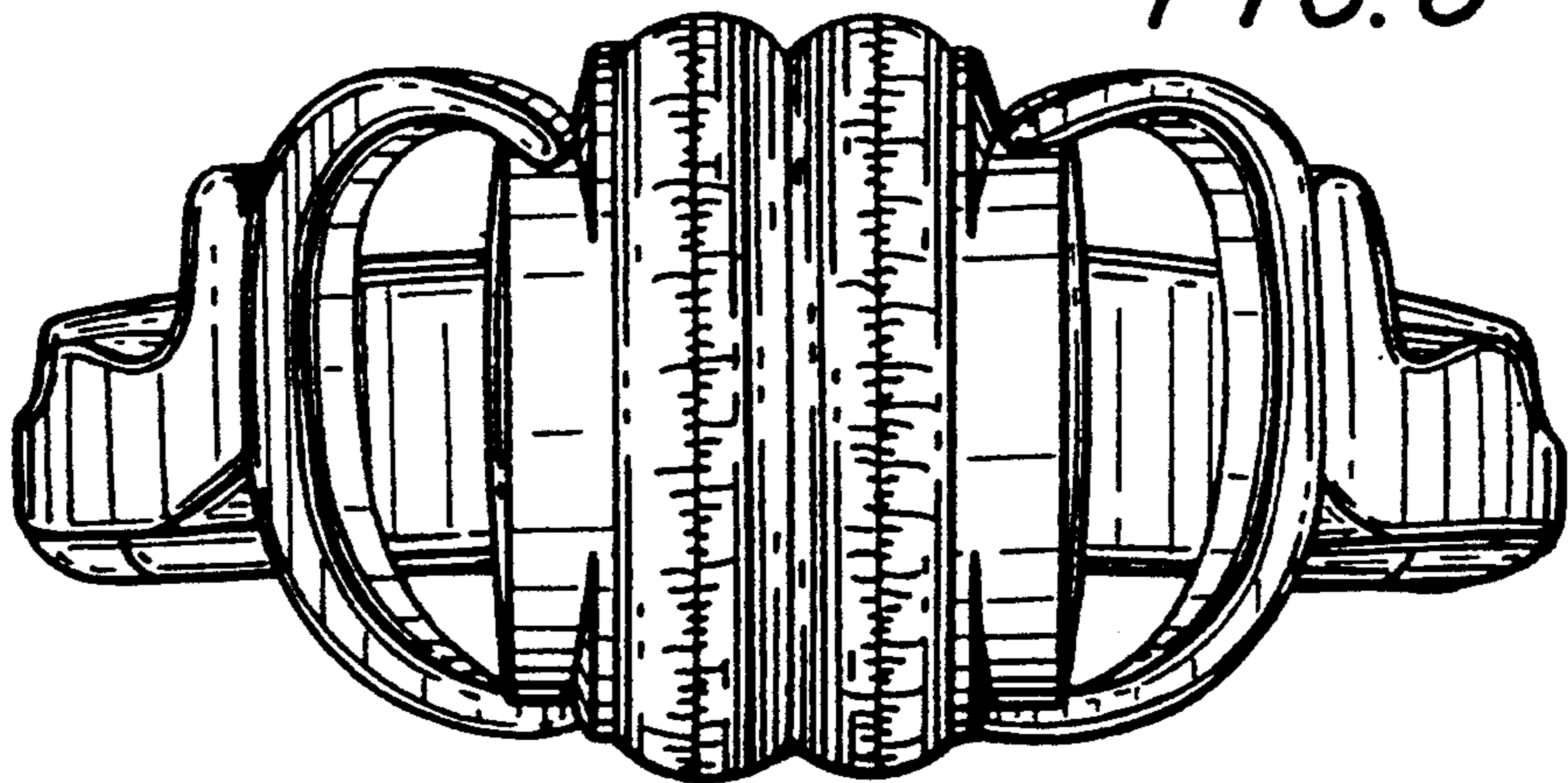
FIG. 5



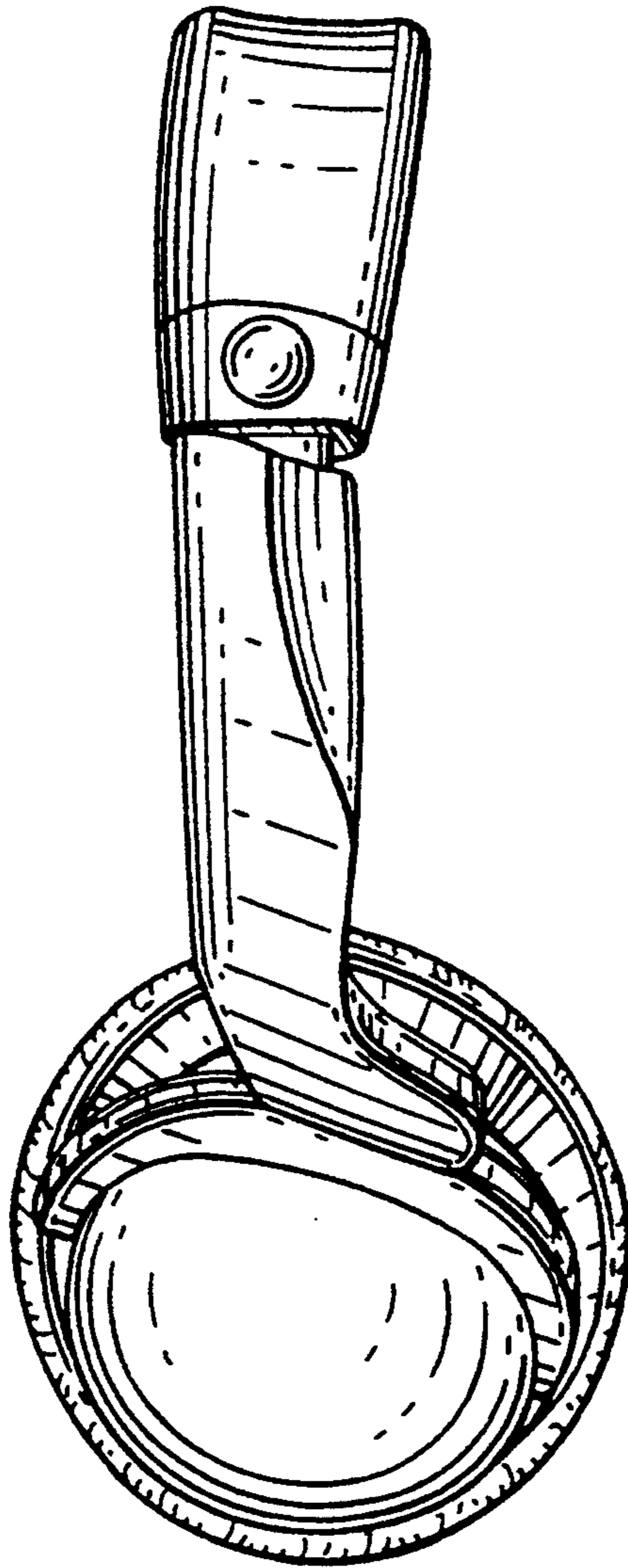
*FIG. 4*



*FIG. 8*



*FIG. 6*



*FIG. 7*

